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INFORMATION DISCLOSURE STATEMENT BY APPLICANT	Application Number	09/845881
(Use as many sheets as necessary)	Filing Date	April 30, 2001
	First Named Inventor	Vu, Quat
2 2 2004	Group Art Unit	2821 2829
MAR 2 2 2004	Examiner Name	Cruz, Lourdes

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Examiner Initials*	Cite No 1	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T

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